



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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TGS2800 MAIL ROOM

Applicant: Charles W.C. Lin
Title: BUMPLESS FLIP CHIP ASSEMBLY WITH SOLDER VIA
Serial No.: 09/852,824 Filed: May 10, 2001
Examiner: Unknown Group Art Unit: 2812
Atty. Docket No.: P002-2

ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

THIRD PRELIMINARY AMENDMENT

Dear Sir:

Please amend the application as follows.

In the Claims

Add the following claims:

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- 1 95. The method as recited in claim 15, wherein the reflowable material
2 extends continuously between the first and second surfaces in the via hole after the
3 reflowing.
- 1 96. The method as recited in claim 15, wherein the reflowable material is the
2 only material in the via hole that contacts the metallization after the reflowing.
- 1 97. The method as recited in claim 15, wherein the reflowable material is the
2 only material in the via hole that contacts the pad after the reflowing.

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